

Title (en)
OPTOELECTRONIC COMPONENT AND METHOD FOR PRODUCING IT

Title (de)
OPTOELEKTRONISCHES BAUELEMENT UND VERFAHREN ZU DESSEN HERSTELLUNG

Title (fr)
COMPOSANT OPTOÉLECTRONIQUE ET SON PROCÉDÉ DE FABRICATION

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Application
EP 11755034 A 20110822

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Abstract (en)
[origin: WO2012034826A1] An optoelectronic component is specified, comprising a carrier (3), which has a first (1) and a second connection region (2), and comprising a radiation-emitting semiconductor chip (4), which has a base surface (5) and a radiation exit surface (6), opposite the base surface, wherein the semiconductor chip (4) is arranged by the base surface (5) on the carrier (3). Furthermore, the optoelectronic component comprises a housing (10) having a lower housing part (8), which adjoins side flanks (14) of the semiconductor chip (4), and an upper housing part (9), which forms a reflector (15) for the radiation (16) emitted by the semiconductor chip (4). An electrical connection layer (7) is led from the radiation exit surface (6) of the semiconductor chip (4) via a part of the interface (19) between the lower (8) and the upper housing part (9) and through the lower housing part (8) to the first connection region (1) on the carrier (3). An advantageous method for producing the optoelectronic component is furthermore specified.

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